



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2823
Examiner: R. Shukla

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In Re PATENT APPLICATION Of:

Applicant(s) : Yasuo TANAKA

Serial No. : 09/660,484

Filed : September 12, 2000

METHOD OF MANUFACTURING
SEMICONDUCTOR DEVICE

Attorney Ref. : OKI 262

AMENDMENT

March 7, 2002

Commissioner for Patents
Washington, D.C. 20231

Sir:

This Amendment is filed in response to the Official Action dated December 21, 2001, the time for response to which is up to and including March 21, 2002. Please amend the above-referenced application as follows.

IN THE CLAIMS

Please cancel claim 2.

Please amend claims 1, 3 and 7-9 to read as follows:

1. (Amended) A method of manufacturing semiconductor devices, comprising:
forming a plurality of semiconductor devices on a main surface of a
semiconductor wafer, the plurality of semiconductors having a plurality of electrode
pads for respectively connecting thereto;
forming a plurality of bumps on said main surface that are respectively
connected to said electrode pads;
placing a sheet of encapsulating material containing a thermosetting resin having

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